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# **Magnetic Tunnel Junction based non-volatile Magnetoresistive RAM**

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# Outline

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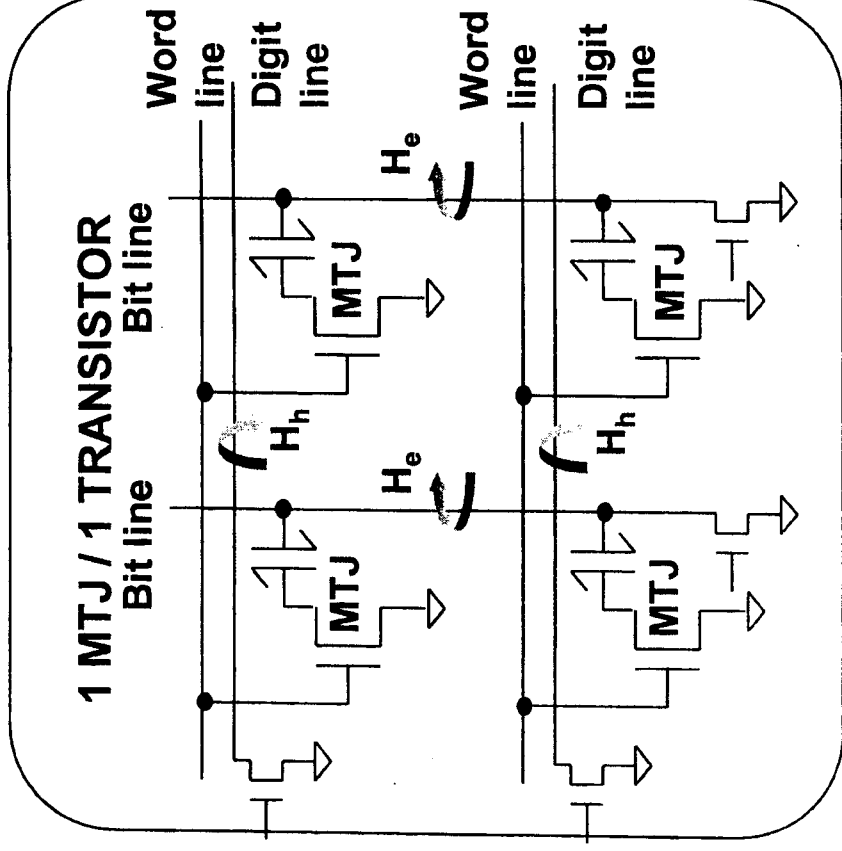
- MRAM attributes
- MRAM cell architecture
- Magnetic Tunnel Junction (MTJ) bit characteristics
- MTJ/CMOS integration challenges and results
- Integrated circuit demonstration results



# MTJ Memory Cell Architecture

## Attributes:

- Nonvolatile
- High Density  $8 - 20F^2$
- No Refresh
- Nondestructive Read
- Low voltage operation
- Unlimited R/W endurance



Cell is defined by a single MTJ and a transistor



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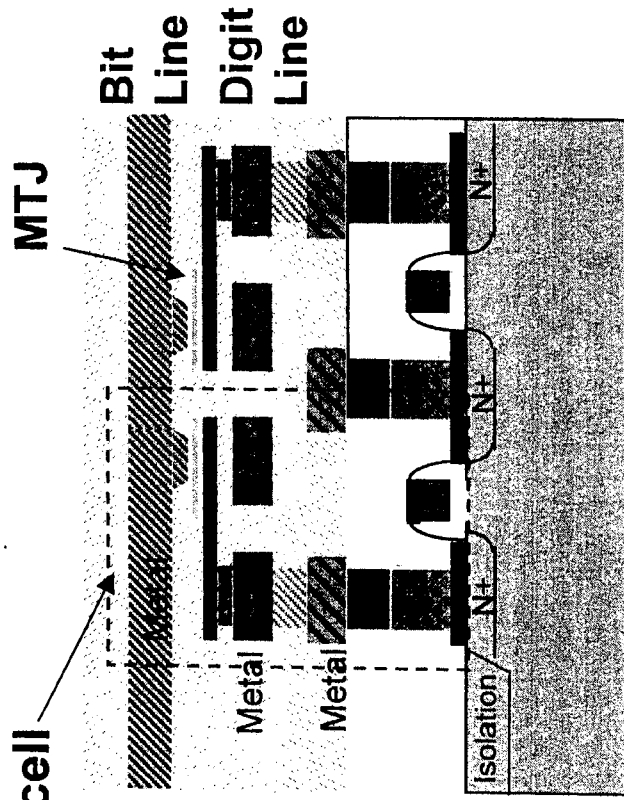
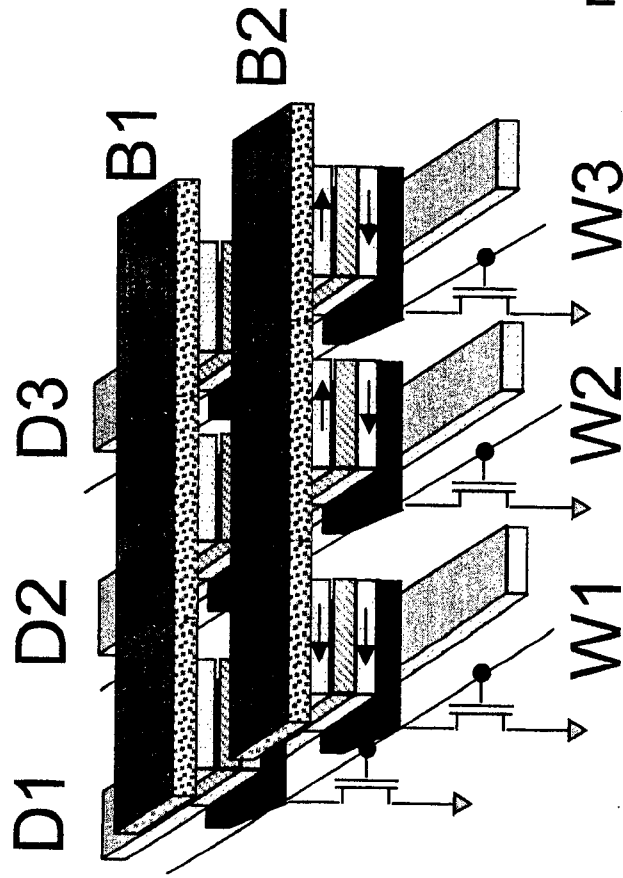
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# Technology Comparison

Attribute	SRAM	DRAM	FLASH	FRAM	Projected MRAM
Read Time	fast	mod.	mod.	mod.	mod.-fast
Write Time	fast	mod.	slow	mod.	mod.-fast
Non-Volatile	no	no	yes	destructive & fatigue	yes
Refresh	NA	ms	NA	NA	NA
Minimum Cell Size	large	small	small	medium	small
Low Voltage	yes	limited	no	limited	yes

# MTJ Memory Cell Architecture

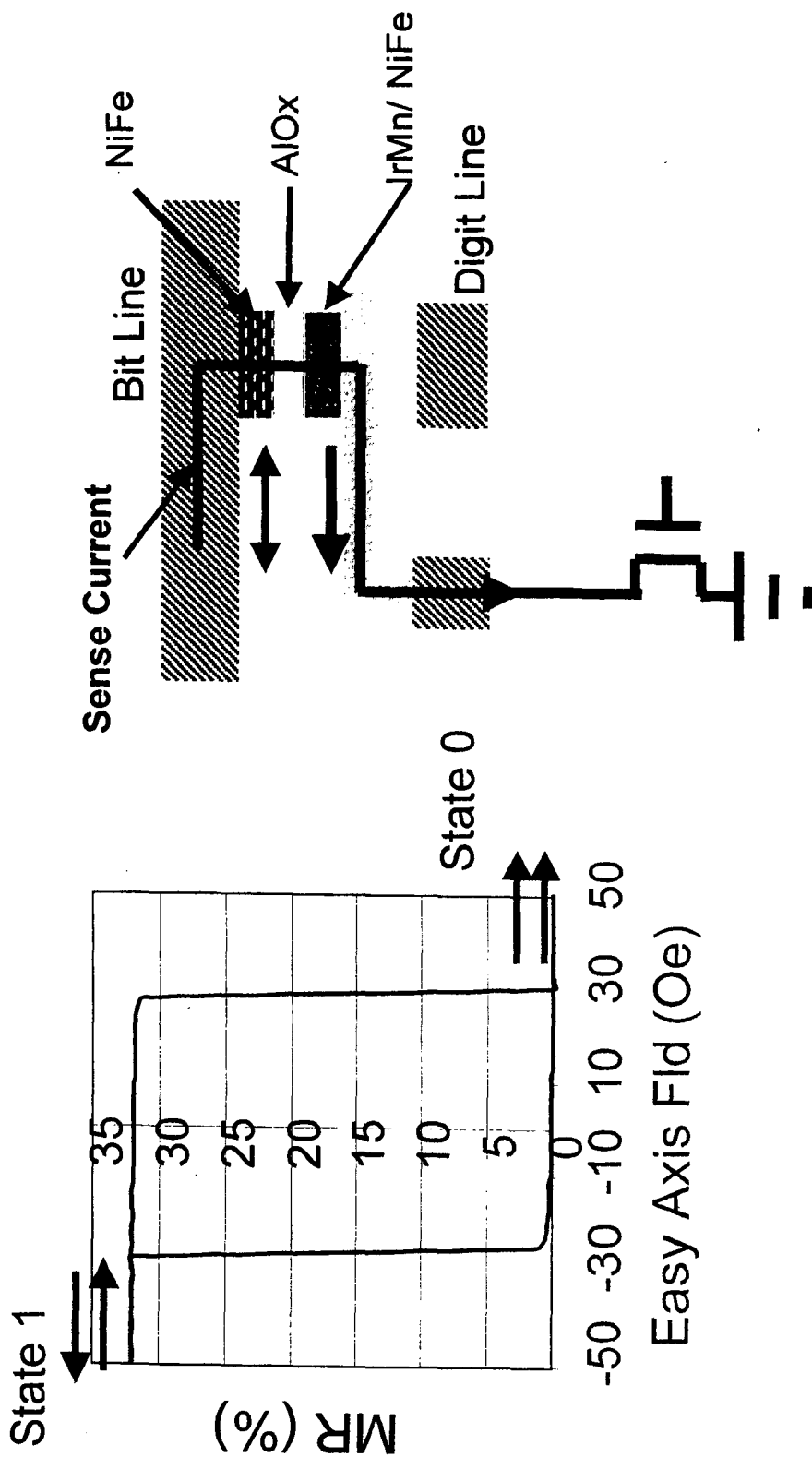
Cross Point matrix of Bit and Digit lines



Magnetic Tunnel Junction (MTJ) MRAM

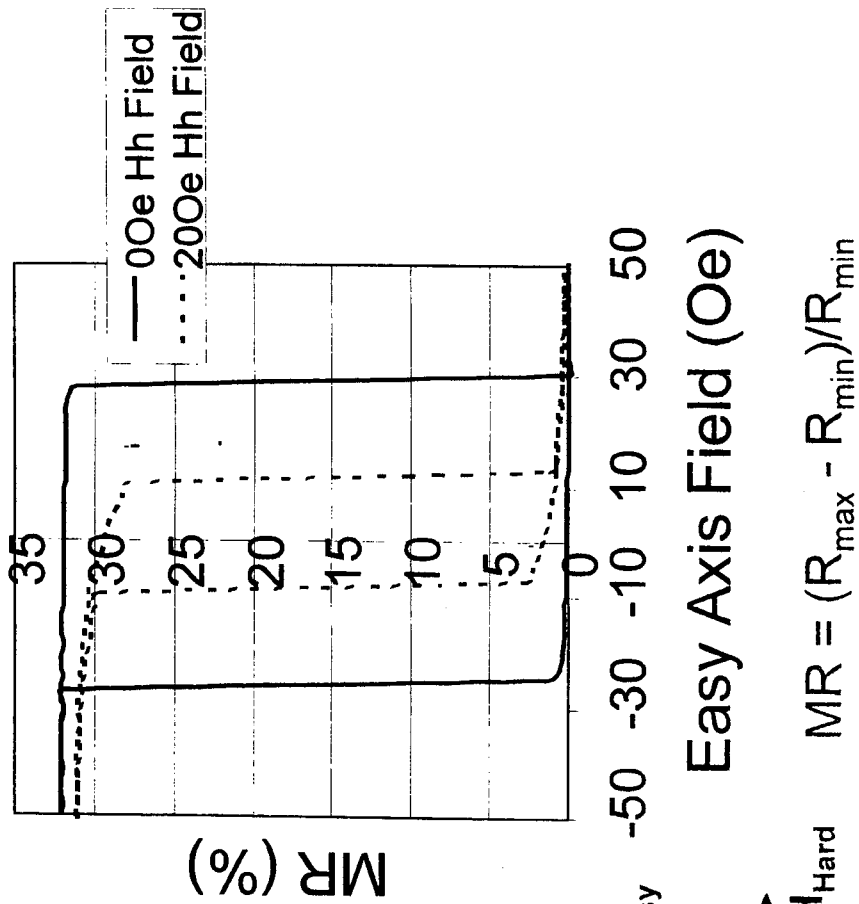
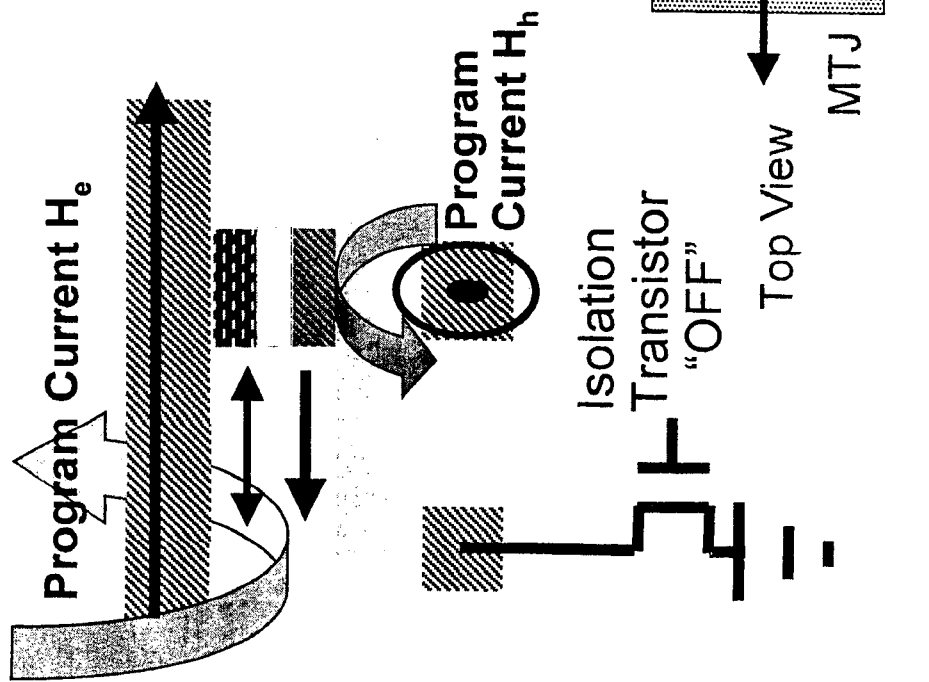


# MTJ Memory Cell Architecture



# MTJ Hysteresis Loop

## Program Mode

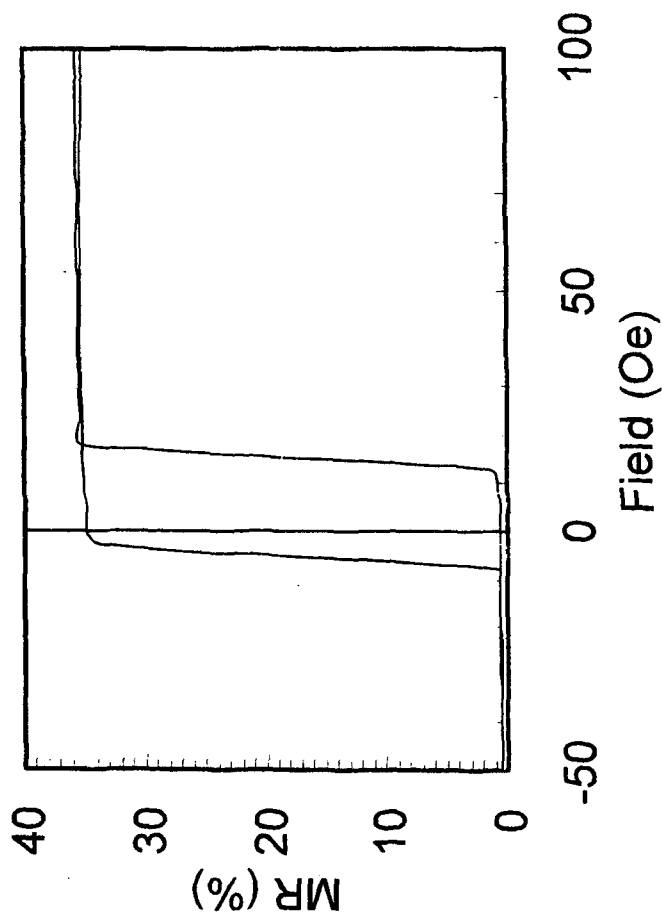


# MTJ characteristics

Transmission Electron Micrograph



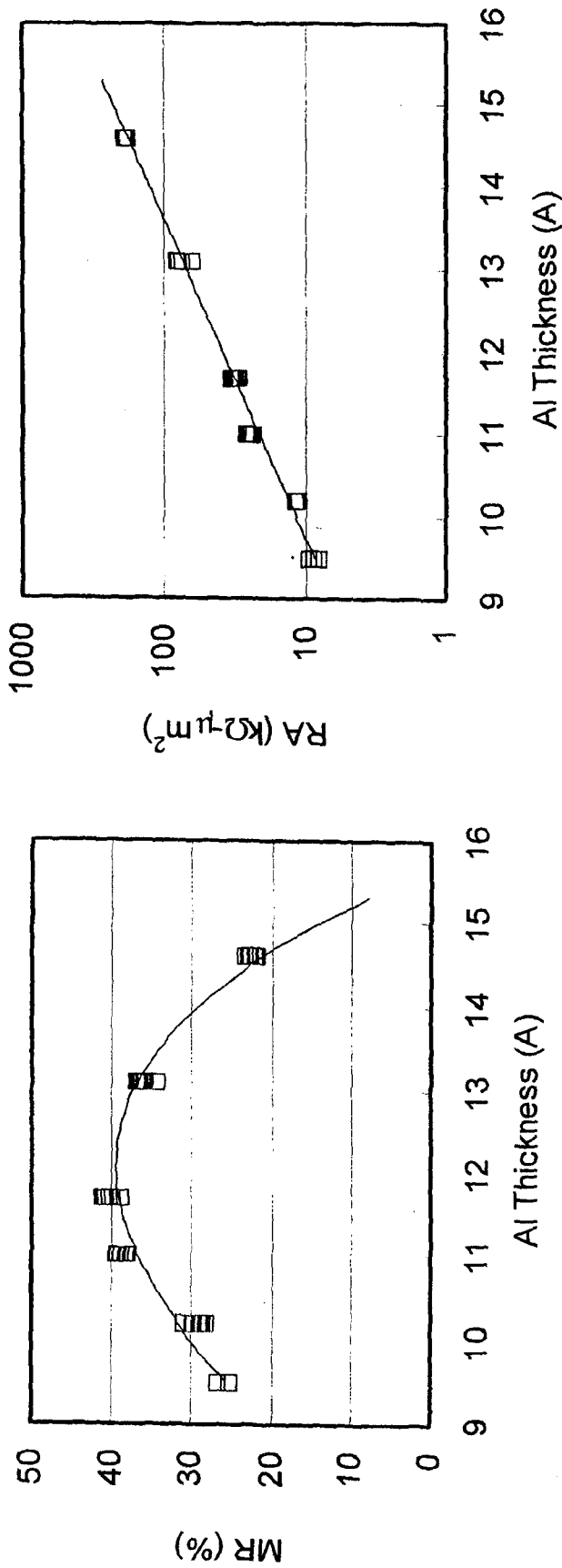
Magnetoresistance Curve





# Aluminum Thickness

*NiFe/AlOx/NiFe*



*Maximum MR=40% with  $d_{Al}=11-12 \text{ \AA}$*

*MR > 20% for RA = 10-100 kΩ-μm<sup>2</sup>*

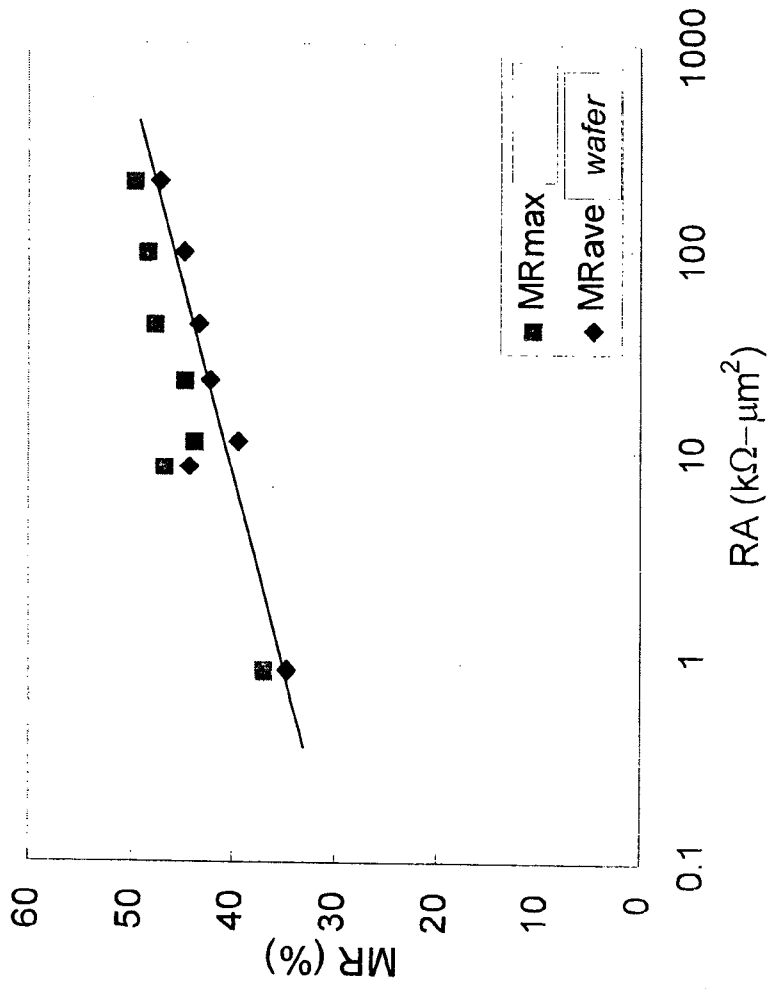


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# MR vs. Resistance

CoFe/ AlOx/ NiFe Tunnel Junction

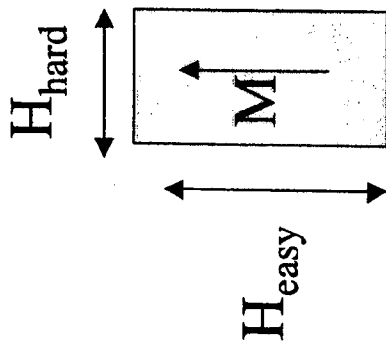


MR average within die

48.2	47.8	46.1
44.9	47.5	47.4
45.2	48.3	46.0
44.6	44.3	46.9
46.7	48.1	45.7
46.3	48.2	47.9
44.6	35.5	41.8

Wafer average = 47.2%

# MRAM write operation

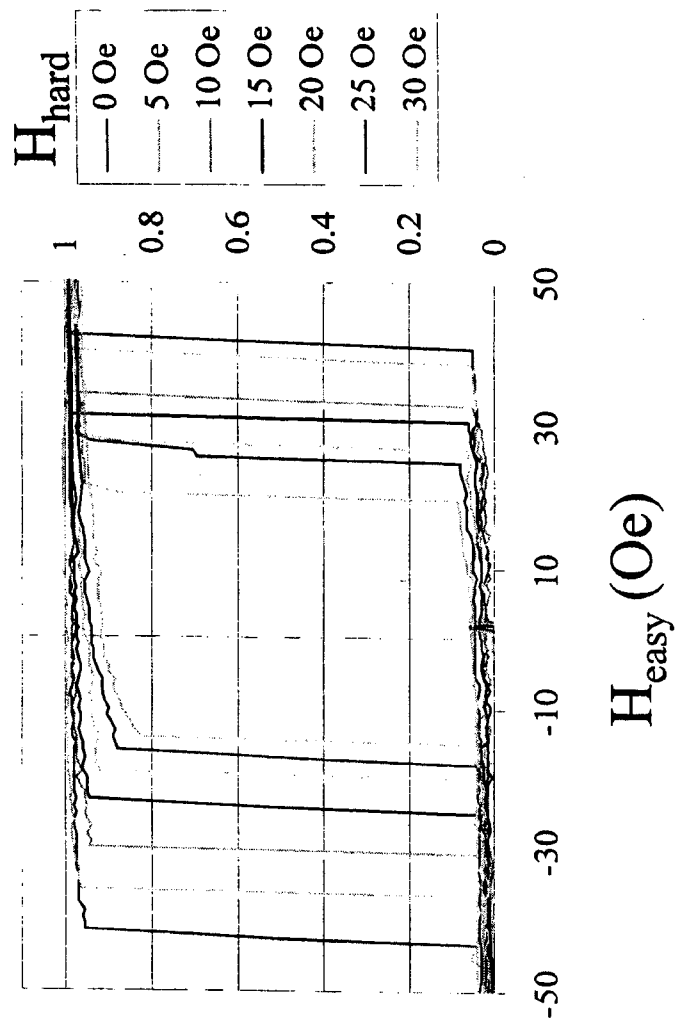


- Shape anisotropy creates energy barrier to reversal

$$E_b \propto N_{\text{eff}} M^2$$

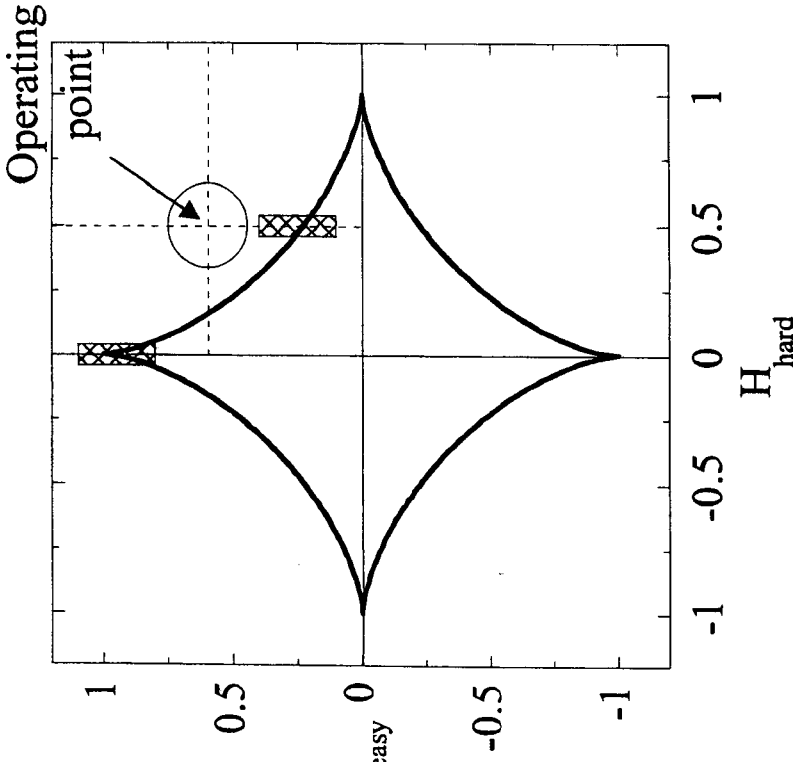
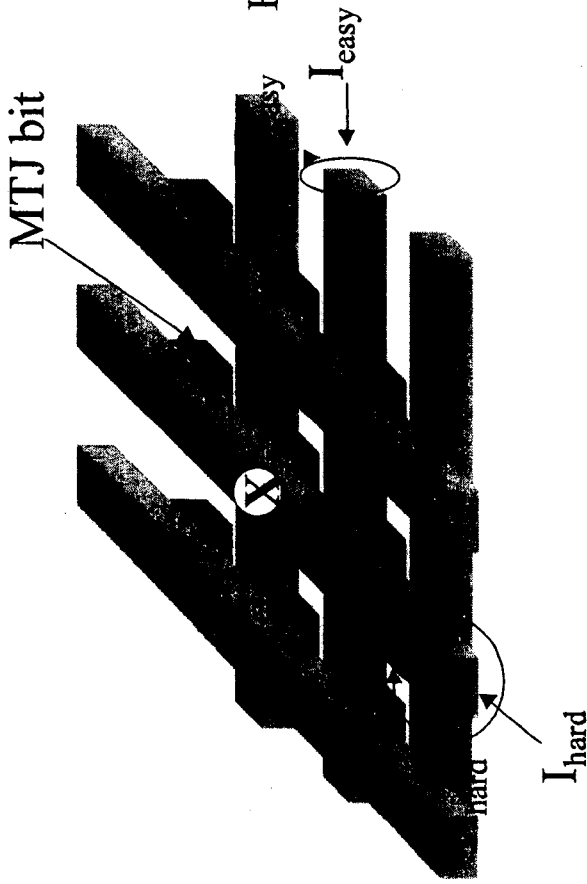
- Hard axis field decreases  $H_c$

Quasistatic hysteresis loops



# MRAM write operation

Cross-point architecture



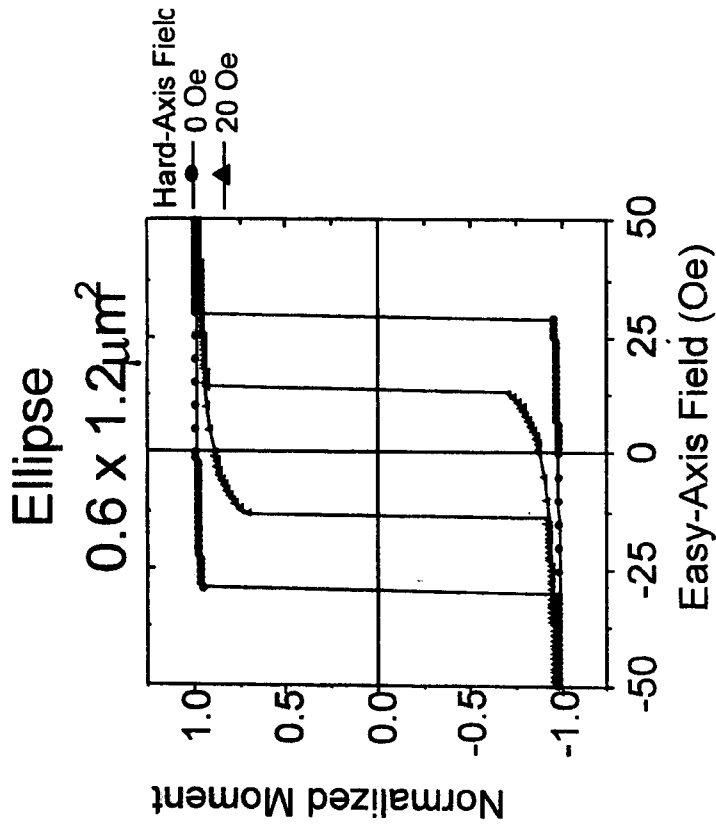
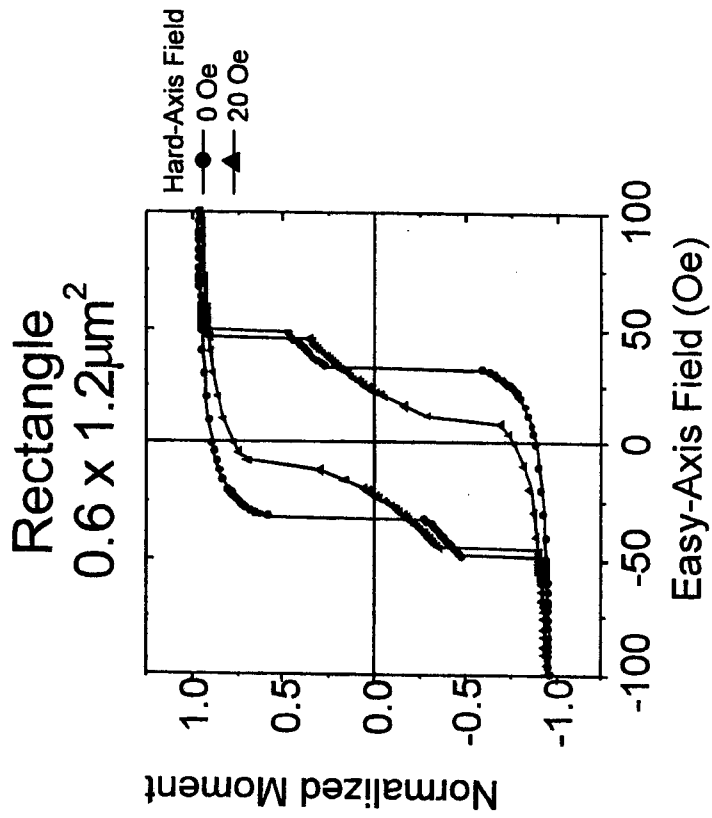
- Need good hard axis response and narrow switching distributions for write selectivity.



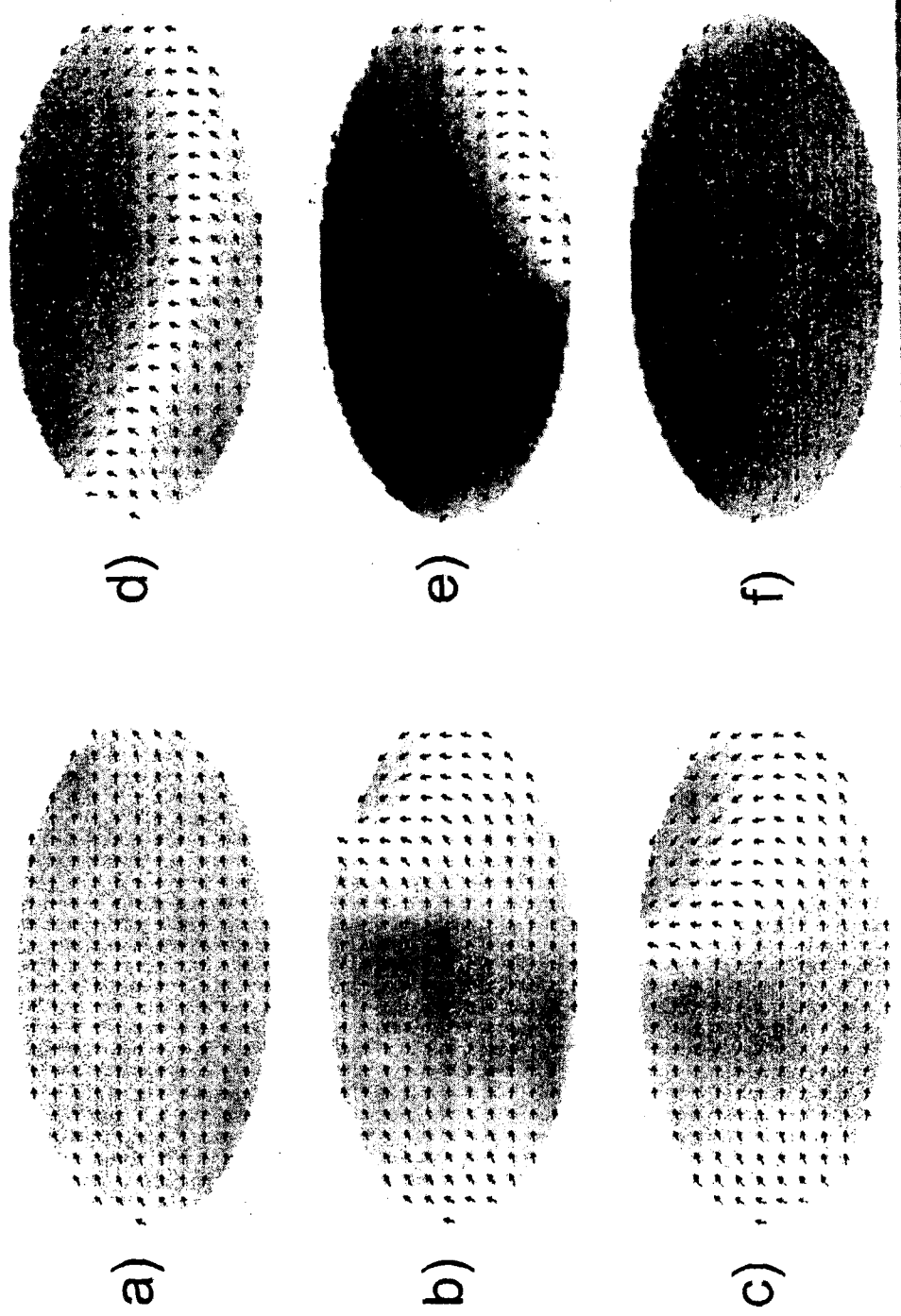
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# Micromagnetic Simulation



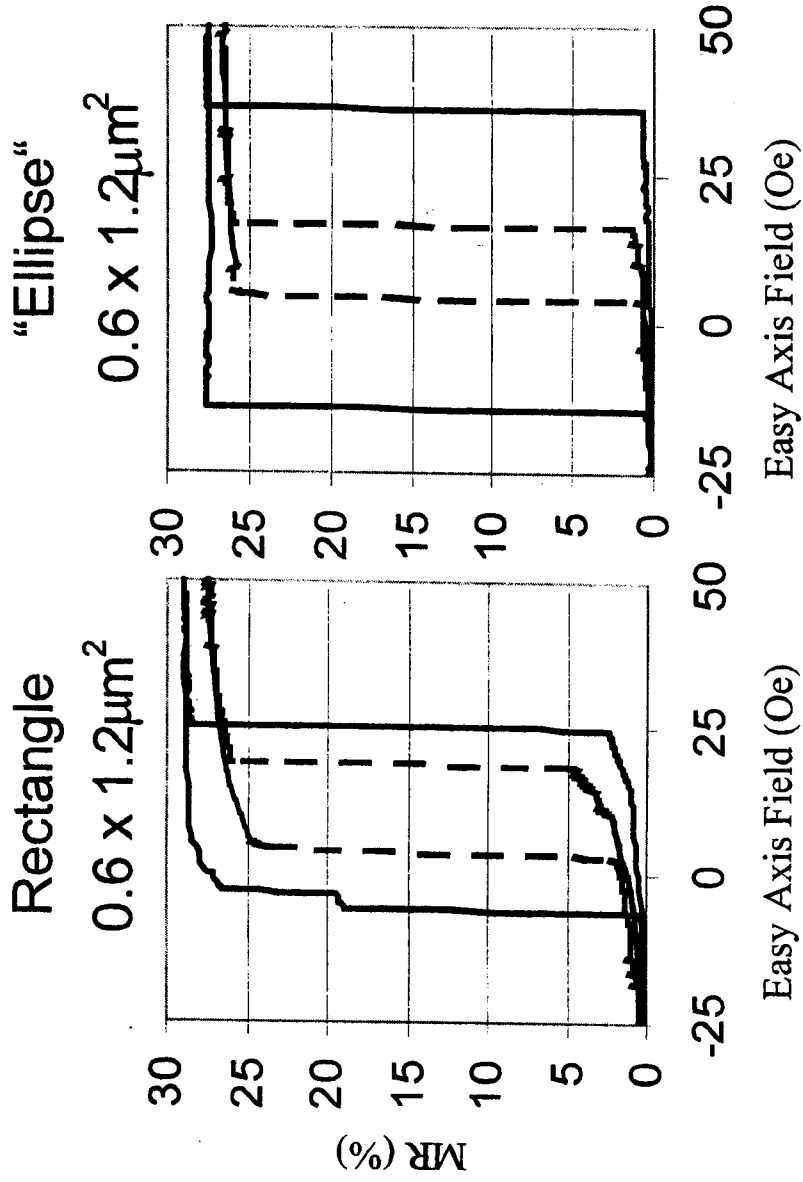
# Micromagnetic Simulation - Switching Transition



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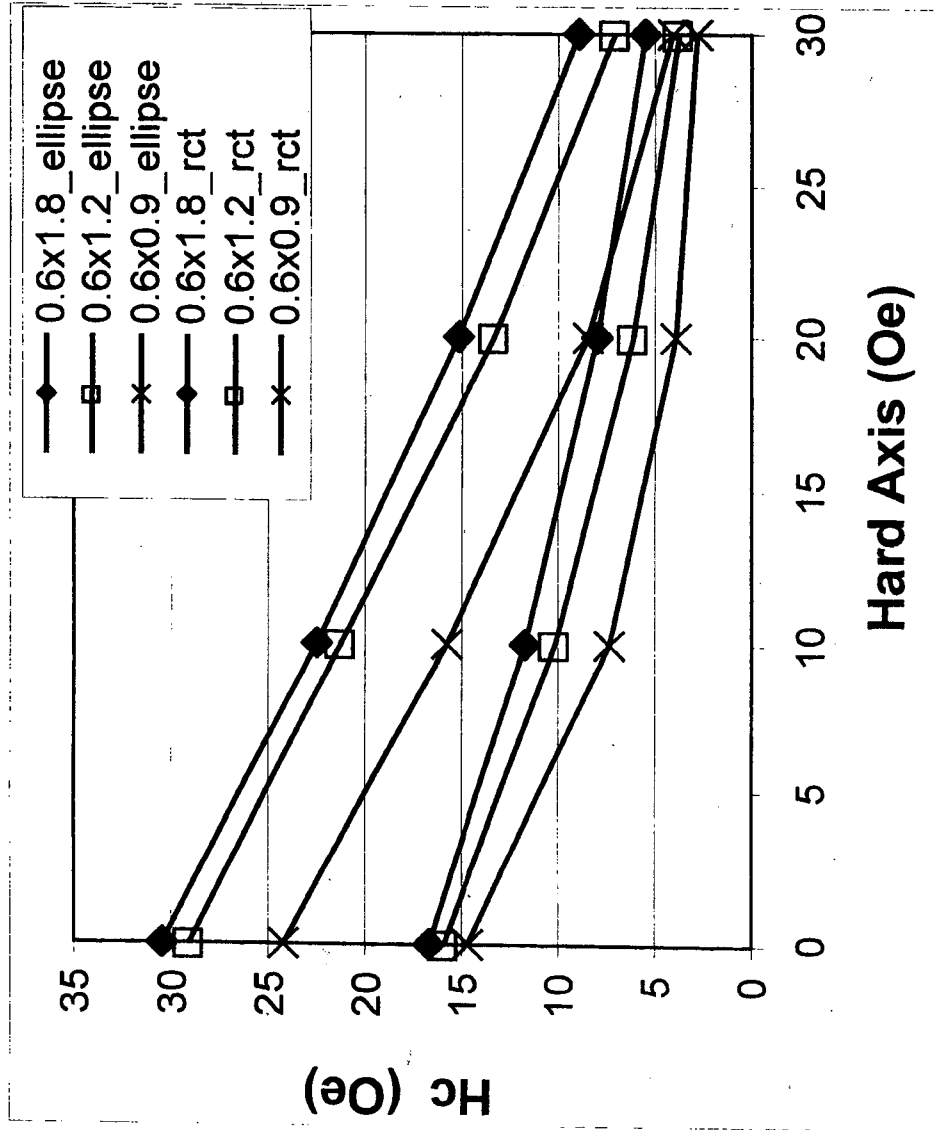
# Experimental Electrical data



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# Switching characteristics of the bits



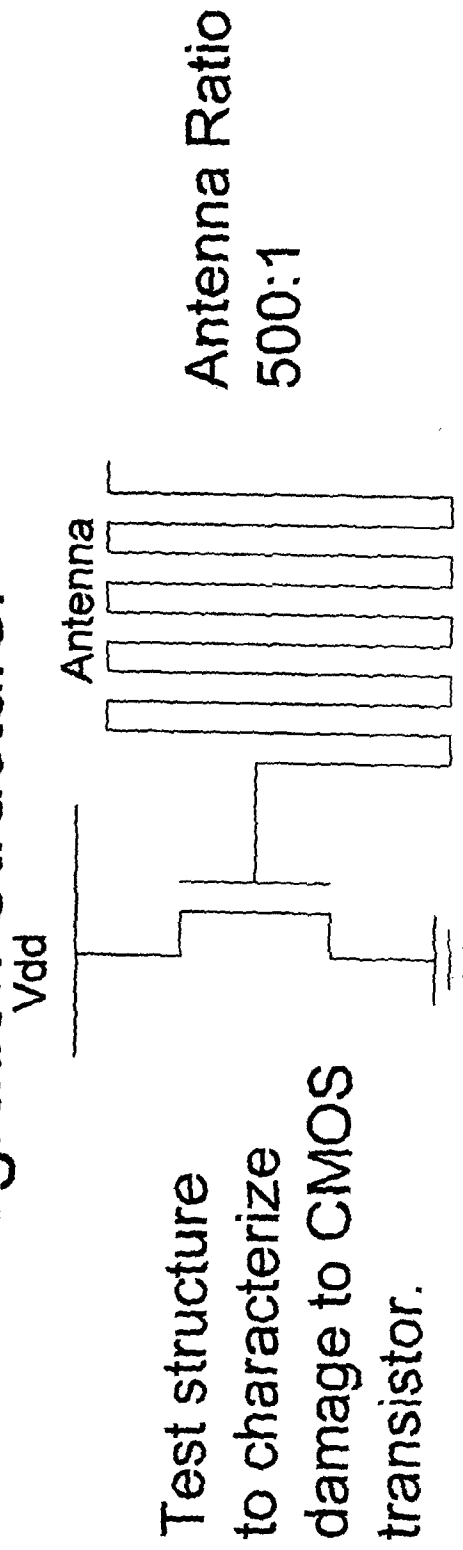


# CMOS/MTJ Integration

## Challenges to Integration:

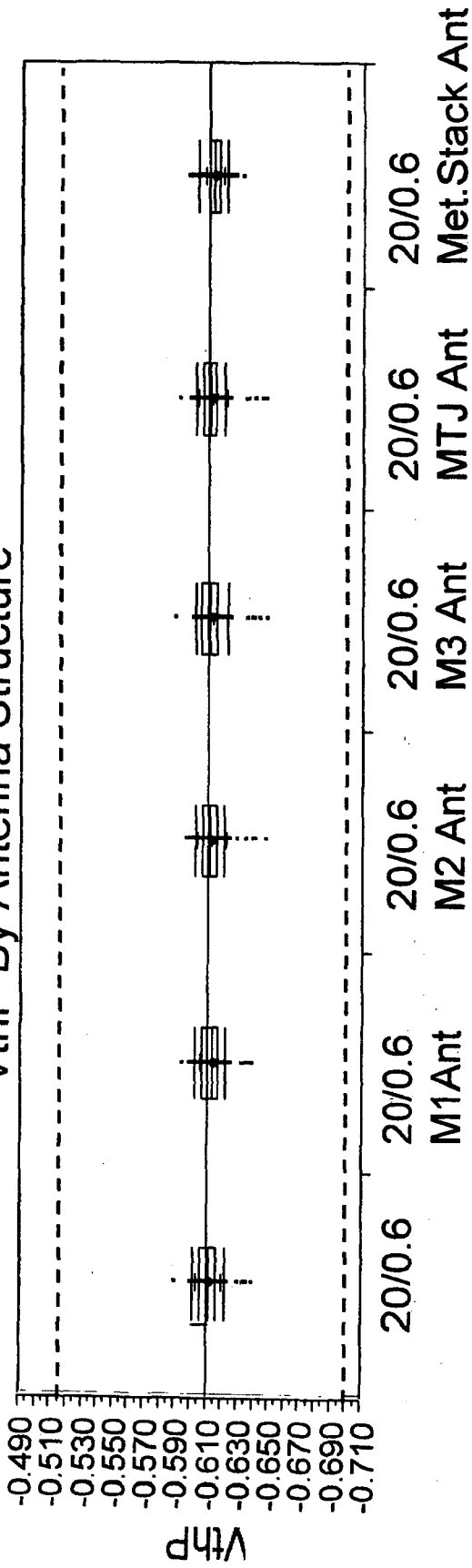
- Threshold voltage shift to CMOS transistors
- Surface roughness under MTJ bit
- Switching characteristics

## CMOS Integration Structure:



# Vt's Post Integration

VthP By Antenna Structure

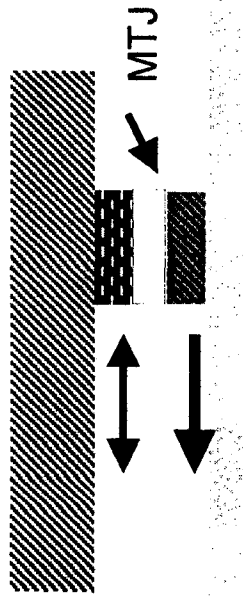


Means and Std Deviations		
Structure	Mean	Std Dev
20/0.6 M1Ant	-0.60922	0.008856
20/0.6 M2 Ant	-0.61095	0.008697
20/0.6 M3 Ant	-0.61011	0.009376
20/0.6 MTJ Ant	-0.61047	0.010557
20/0.6 MTJ Ant	-0.61001	0.009450
20/0.6 MStack Ant	-0.61102	0.006926



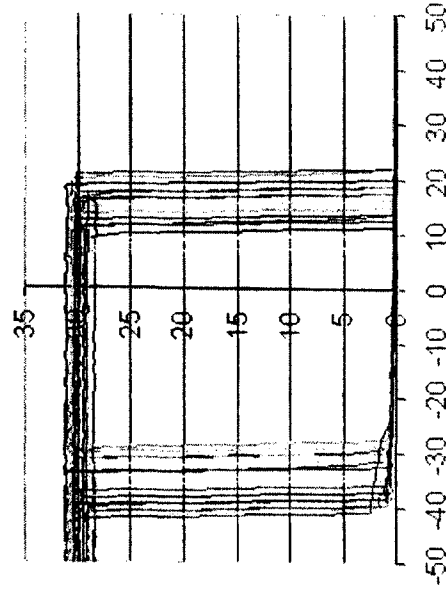
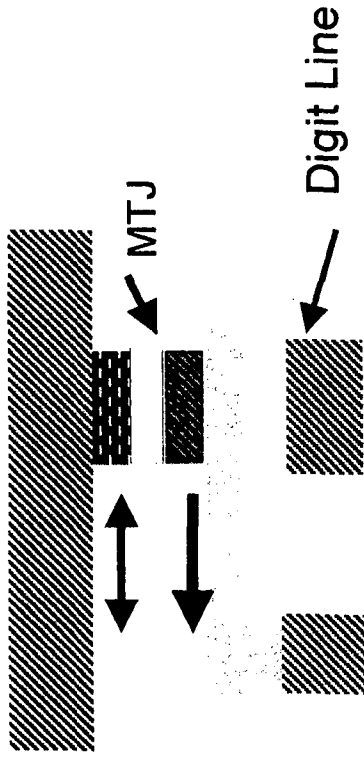
# Roughness induced by Digit Line

Bits without Digit Line

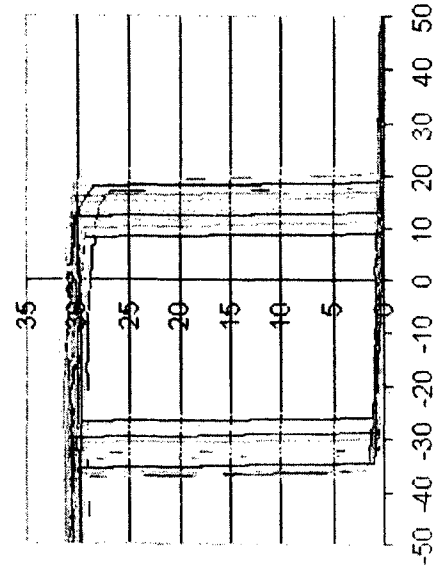


SiON dielectric

Bits with Digit Line



After Optimization  
(0.6x1.2μm bits shown)



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# CMOS Integration - 1T/1MTJ Cell

0.6x1.2  $\mu\text{m}$  bits @ 200mV bias with access Transistor

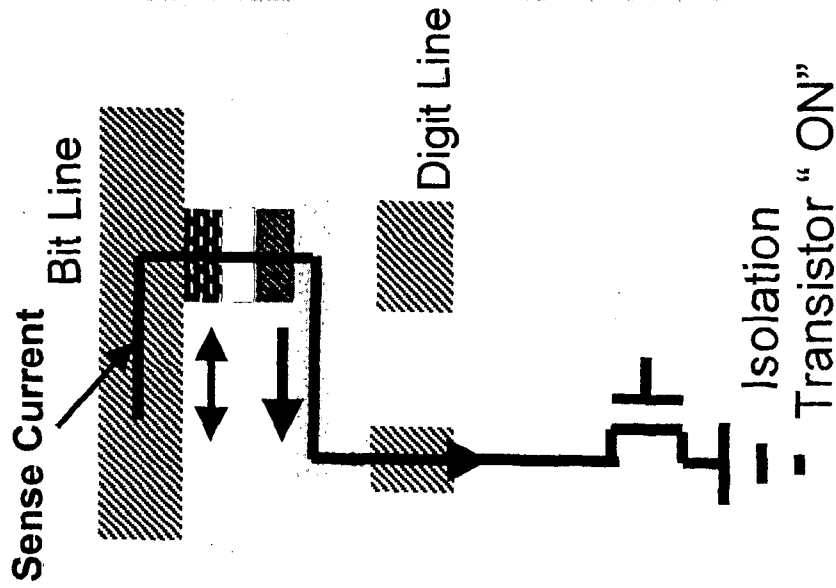
Wafer Map of R-A ( $\text{k}\Omega\text{-}\mu\text{m}^2$ )

13	12	12	12
11	11	9.3	8.4
13	9.7	8.4	7.6
15	6.8	6	7.1
14	11	8.3	7.6
15	12	11	9.3
18	13	12	

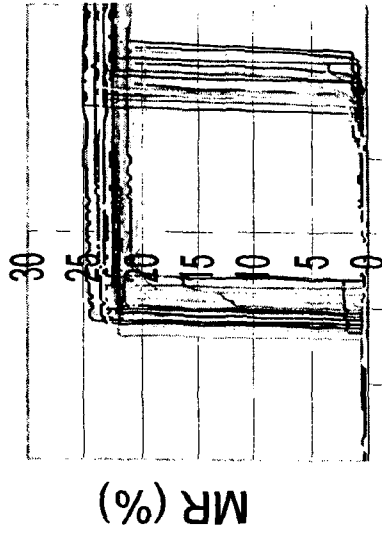
Wafer Map of MR (%)

23	23	23	24	22
22	23	22	22	22
23	22	22	21	20
21	19	18	21	20
25	23	22	21	22
23	24	23	22	22
25	22	23		

150 mm wafer



no digit line current

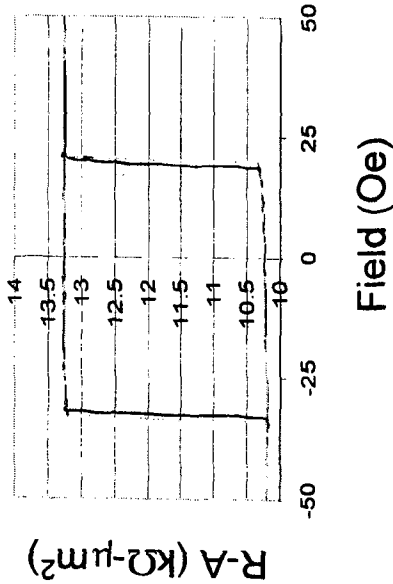


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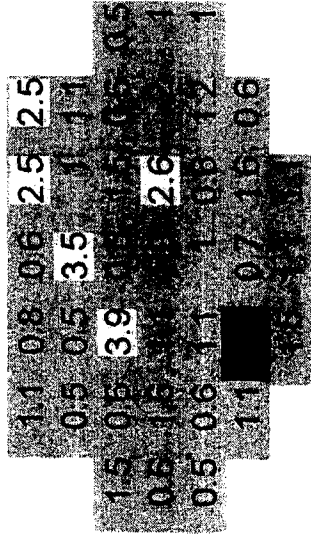
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# Uniformity vs. Repeatability

Single  $0.6 \times 1.5 \mu\text{m}^2$  bit from array, repeated 15 times

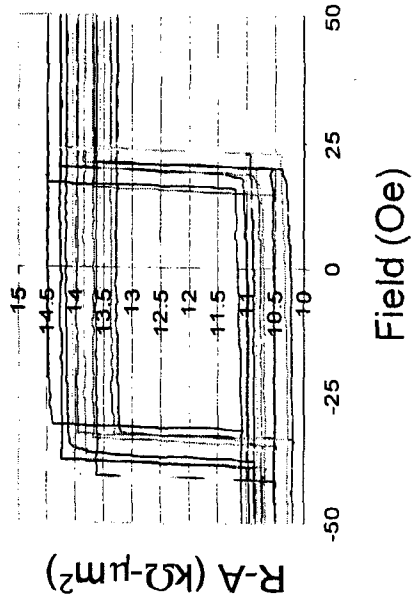


Map of spread in coercivity (Oe)

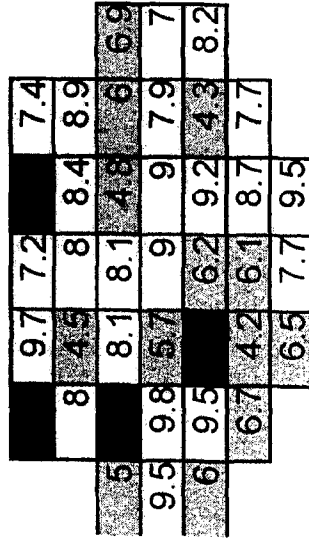


Average  $1.2 \text{ Oe} \pm 0.6 \text{ Oe}$

15 -  $0.6 \times 1.5 \mu\text{m}^2$  bits in  $1 \text{mm} \times 1.2 \text{mm}$  array



Map of spread in coercivity (Oe)

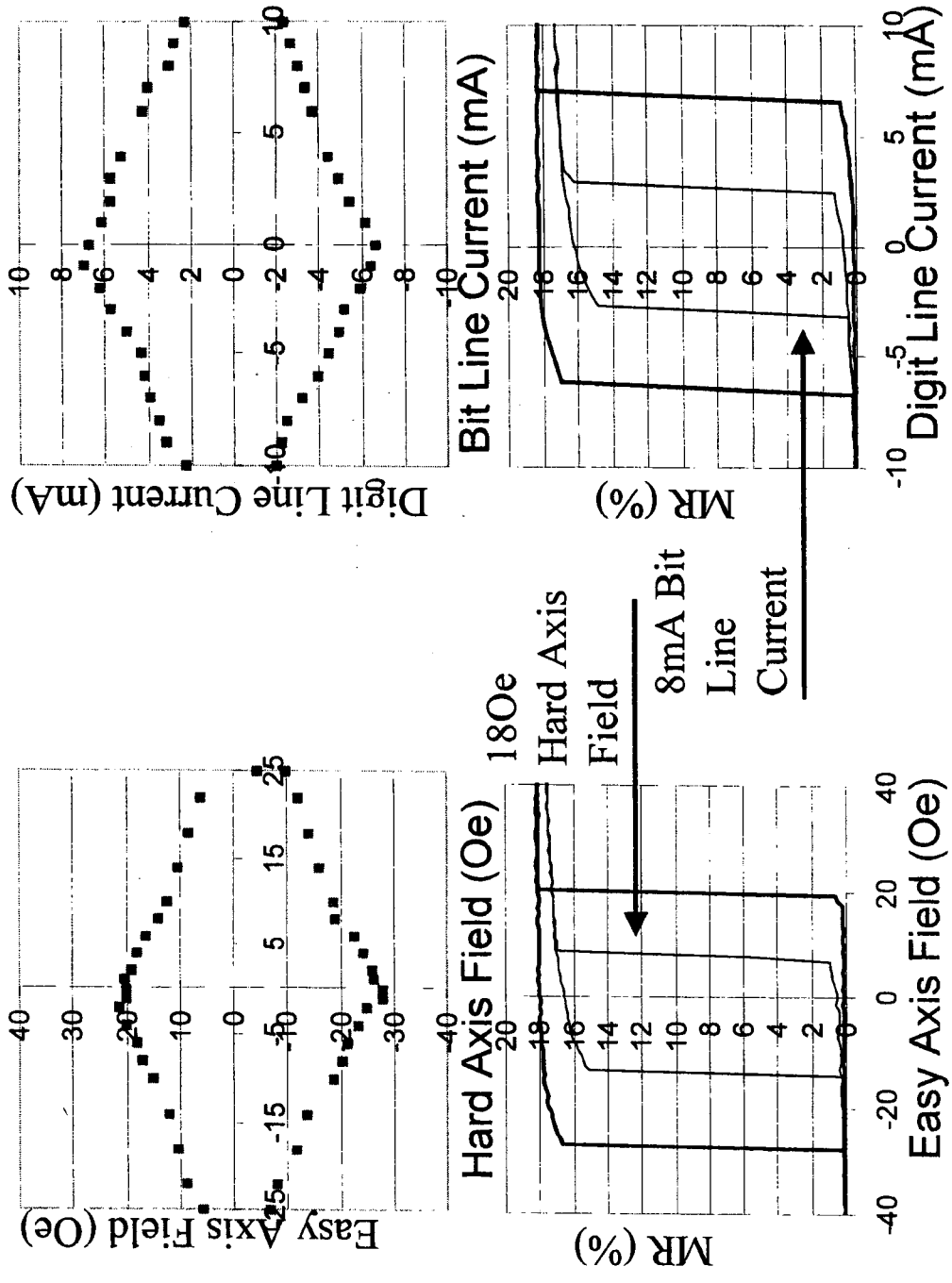


Average  $7.5 \text{ Oe} \pm 1.7 \text{ Oe}$



# External Field vs. Current Switching

Comparison of switching a 0.6x2.1  $\mu\text{m}^2$  bit with external field versus lines near bit.



# MRAM Memory

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## 256 x 2 MRAM

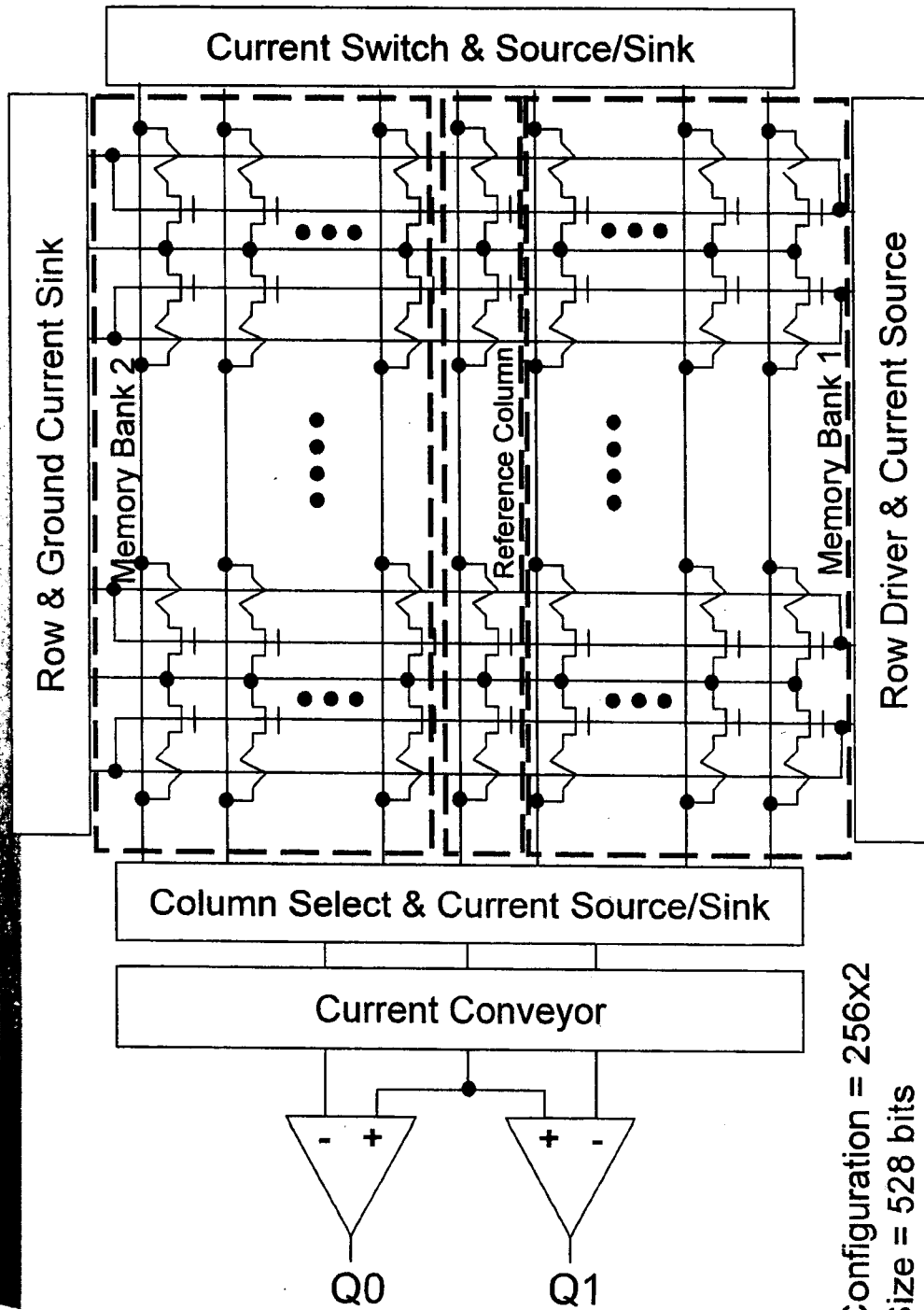
- Non-volatile Random Access Memory
- 1 MTJ / 1 Transistor Cell
- 7.1  $\mu\text{m}^2$  cell area in 0.6  $\mu\text{m}$  CMOS process
- 16 rows, 32 columns, and 1 reference column
- Current mode read operation
- Reference column allows excellent tracking between target and reference bitline signals and provides a adequate level of Common Mode Rejection (CMR)



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# 512 Array Schematic

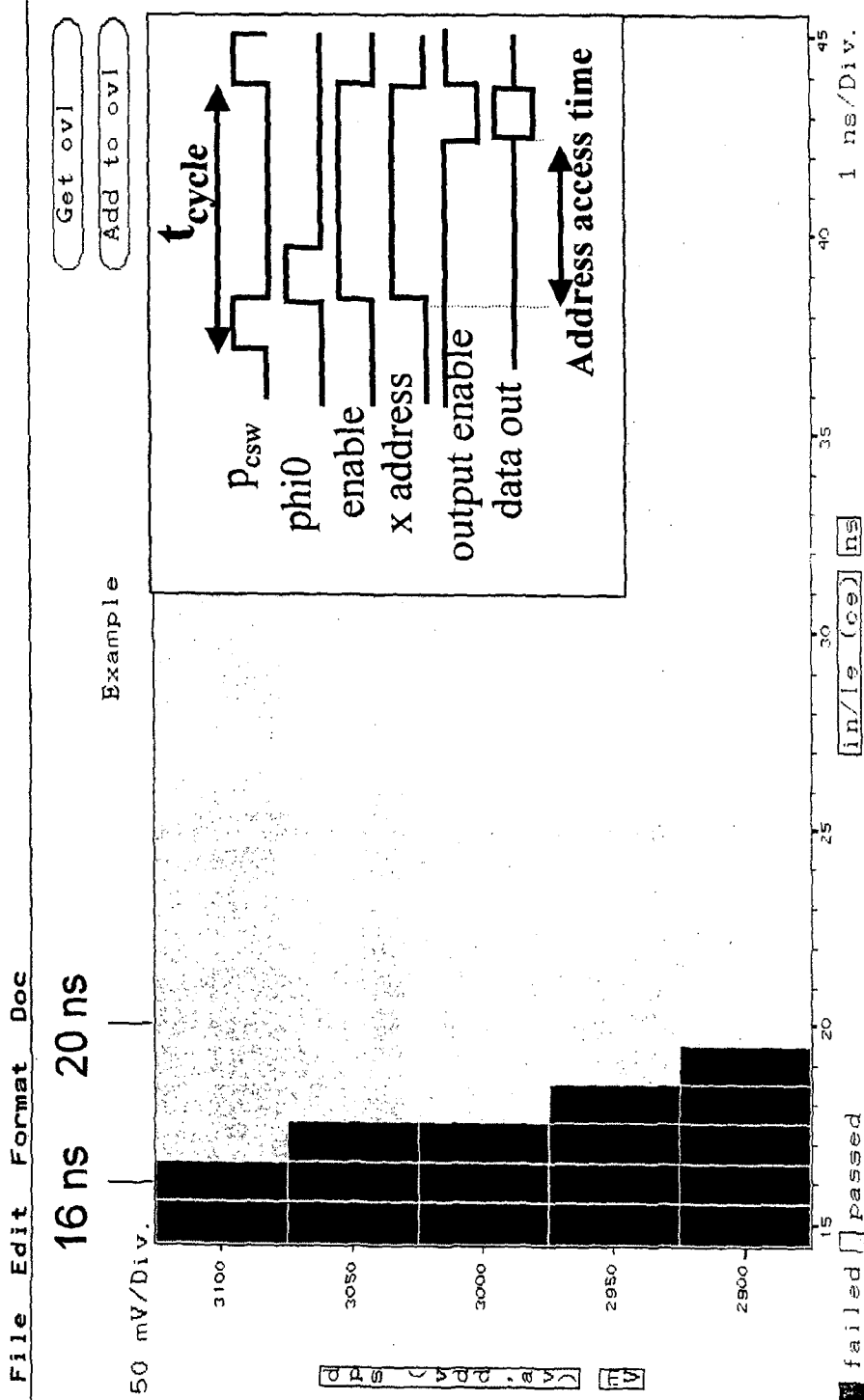


Configuration = 256x2  
 Size = 528 bits





# Shmoo Plot of $t_{\text{access}}$ vs. VDD



(24)

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# Summary

- Demonstrated uniform MR and resistance across 6 inch wafer
- Demonstrated successful integration of MTJ and CMOS
- Measured address access time of 8ns and read cycle time of 18ns for 256x2 arrays at 3.0V using a single transistor and MTJ for a cell

